PATENT ASSIGNMENT

Electronic Version v08
Stylesheet Version v02

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT OF ASSIGNOR'S INTEREST

CONVEYING PARTY DATA

Name	Execution Date
Jin-Yuan Lee	2002-01-18
Mou-Shiung Lin	2002-01-18
Ching-Cheng Huang	2002-01-18

RECEIVING PARTY DATA

Name	Street Address	Internal Address	City	State/Country	Postal Code
MEGIC Corporation	21, R&D 1ST. Rd., Science-Based Industrial Park Hsinchu		Hsin-Chu City	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number	10454972

CORRESPONDENCE DATA

FAX NUMBER: 8064986673
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.
CUSTOMER NUMBER: 027765

NAME OF PERSON SIGNING:	WINSTON HSU
DATE SIGNED:	2005-11-16

Total Attachments: 2
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ASSIGNMENT

WHEREAS,
1. Mou-Shiung Lin
2. Jin-Yuan Lee
3. Ching-Cheng Huang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

METHOD FOR FABRICATING CHIP PACKAGE WITH DIE AND SUBSTRATE

Title: ~~**INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME**~~

W. Hsu
Reg. No. 41526
11/11/2005

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Megic Corporation
of 21, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature — Date 1/18/2002

Sole or First Joint Inventor: Mou-Shiung Lin

Jin-Yuan Lee
Signature — Date 1/18'02

Second Joint Inventor (if any): Jin-Yuan Lee

Ching-Cheng Huang
Signature — Date 1/8/2002

Third Joint Inventor (if any): Ching-Cheng Huang